

SID

Factory: Rot am See

Article:

508

ML6

Provided:

Kracht, Enrico

Customer:

Date:

10.08.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	132		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.20mm-018+018-TG150-HF	50200652	18	L2	4	A01
		200			
		18	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	122		5	B00
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6	
A-RS-FR4-ML-0.20mm-018+018-TG150-HF	50200652	18	L4	7	A02
		200			
		18	L5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	132		8	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		9	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	10	

Thickness after Pressing

B00:

940 µm

Tol+:

105 µm

Tol-:

105 µm

Dmax:

1045 µm

Dmin:

835 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1050 µm

Tol+:

105 µm

Tol-:

105 µm

Dmax:

1155 µm

Dmin:

945 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

894 µm

Version 1.2.14.15

© Würth Elektronik